# General Purpose Peak EMI Reduction IC

#### **Functional Description**

PCS3P8504A is a versatile, 3.3 V Timing–Safe<sup>™</sup> Peak EMI reduction IC. PCS3P8504A accepts an input clock either from a fundamental Crystal or from an external reference (AC or DC coupled to XIN/CLKIN) and locks on to it delivering a 1x modulated clock output. PCS3P8504A has a SSON pin for enabling and disabling Spread Spectrum function.

PCS3P8504A has an SSEXTR pin to select different deviations depending upon the value of an external resistor connected between SSEXTR and GND. Modulation Rate (MR) control selects one of the two different Modulation Rates.

PCS3P8504A operates from a 3.3 V supply, and is available in an 8-pin, WDFN(2 mm x 2 mm) package.

## **General Features**

- 1x, LVCMOS Peak EMI Reduction
- Input frequency:
- ◆ 15 MHz 50 MHz
- Output frequency:
  - ◆ 15 MHz 50 MHz
- Analog Deviation Selection
- ModRate selection option
- Spread Spectrum Enable/Disable
- Supply Voltage:  $3.3 \text{ V} \pm 0.3 \text{ V}$
- 8–pin, WDFN 2 mm x 2 mm (TDFN) Package
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

#### Application

• PCS3P8504A is targeted for consumer electronics application like DPF, MFP.



## **ON Semiconductor®**

#### www.onsemi.com



= Pb–Free Device

(Note: Microdot may be in either location)



## ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

1



### Figure 1. Block Diagram

#### Table 1. PIN DESCRIPTION

Pin#	Pin Name	Туре	Description
1	XIN / CLKIN	Ι	Crystal connection or External reference clock input.
2	XOUT	0	Crystal connection. If using an external reference, this pin should be left open.
3	SSON	I	Spread Spectrum ON/OFF. Spread Spectrum function enabled when HIGH, disabled when LOW. Has an internal pull–up resistor.
4	GND	Р	Ground
5	ModOUT	0	Modulated clock output
6	MR	Ι	Modulation Rate Select. When LOW selects Low Modulation Rate. Selects High Modulation Rate when pulled HIGH. Has an internal pull-up resistor.
7	SSEXTR	Ι	Analog Deviation Selection through external resistor to GND.
8	V <sub>DD</sub>	Р	3.3 V supply Voltage.

#### **Table 2. OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit
V <sub>DD</sub>	Supply Voltage	3	3.6	V
T <sub>A</sub>	Operating Temperature Industrial	-40	85	°C
CL	Load Capacitance		10	pF
C <sub>IN</sub>	Input Capacitance		7	pF

## Table 3. ABSOLUTE MAXIMUM RATING

Symbol	Symbol Parameter		Unit
V <sub>DD</sub> , V <sub>IN</sub>	V <sub>DD</sub> , V <sub>IN</sub> Voltage on any input pin with respect to Ground		V
T <sub>STG</sub>	T <sub>STG</sub> Storage Temperature       T <sub>s</sub> Max. Soldering Temperature (10 sec)		°C
Ts			°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### **Table 3. ABSOLUTE MAXIMUM RATING**

Symbol	Parameter	Rating	Unit
TJ	Junction Temperature	150	°C
T <sub>DV</sub>	Static Discharge Voltage (As per JEDEC STD22– A114–B)	2	kV

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### **Table 4. DC ELECTRICAL CHARACTERISTICS**

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
VDD	Supply Voltage		3.0	3.3	3.6	V
V <sub>IL</sub>	Input LOW Voltage				0.8	V
VIH	Input HIGH Voltage		2.0			V
IIL	Input LOW Current	V <sub>IN</sub> = 0 V			25	μΑ
Ι <sub>ΙΗ</sub>	Input HIGH Current	$V_{IN} = V_{DD}$			25	μΑ
V <sub>OL</sub>	Output LOW Voltage	I <sub>OL</sub> = 8 mA			0.4	V
V <sub>OH</sub>	Output HIGH Voltage	I <sub>OH</sub> = -8 mA	2.4			V
I <sub>CC</sub>	Static Supply Current	XIN / CLKIN pulled low			50	μΑ
I <sub>DD</sub>	Dynamic Supply Current	Unloaded Output			20	mA
Zo	Output Impedance			30		Ω

## Table 5. SWITCHING CHARACTERISTICS

Parameter	Test Conditions	Min	Тур	Max	Unit
Input Frequency* / ModOUT		15		50	MHz
Duty Cycle (Notes 1 and 2)	Measured at V <sub>DD</sub> / 2	45	50	55	%
Output Rise Time (Notes 1 and 2)	Measured between 20% to 80%			1.8	ns
Output Fall Time (Notes 1 and 2)	Measured between 80% to 20%			1.6	ns
Cycle-to-Cycle Jitter (Note 2)	Unloaded output with SSEXTR OPEN @ 27 MHz		±150	±250	ps
PLL Lock Time (Note 2)	Stable power supply, valid clock presented on XIN / CLKIN			3	ms

\*Functionality with Crystal is guaranteed by design and characterization. Not tested in production.
1. All parameters are specified with10 pF loaded outputs.
2. Parameter is guaranteed by design and characterization. Not tested in production.

## TYPICAL CRYSTAL SPECIFICATIONS

## FUNDAMENTAL AT CUT PARALLEL RESONANT CRYSTAL

Nominal frequency	27 MHz
Frequency tolerance	$\pm$ 50 ppm or better at 25°C
Operating temperature range	-25°C to +85°C
Storage temperature	-40°C to +85°C
Load capacitance (C <sub>P</sub> )	18 pF
Shunt capacitance	7 pF maximum
ESR	25 Ω

NOTE: C<sub>L</sub> is the Load Capacitance and Rx is used to prevent oscillations at overtone frequency of the Fundamental frequency.



 $C_L = 2 * (C_P - C_S),$ 

Where  $C_P$  = Load capacitance of crystal from crystal vendor datasheet  $C_S$  = Stray capacitance due to  $C_{IN}$ , PCB, Trace etc.

#### Figure 2. Typical Crystal Interface Circuit

## SWITCHING WAVEFORMS



#### Figure 3. Duty Cycle Timing



Figure 4. Output Rise/Fall Time



Refer to Pin Description table for Functionality details

#### **Figure 5. Application Schematic**



NOTE: Device to Device variation of Deviation is ±10% (Commercial Temperature Range) and ±25% (Industrial Temperature Range)

#### **ORDERING INFORMATION**

Part Number	Top Marking	Temperature	Package Type	Shipping <sup>†</sup>
PCS3P8504AG-08CR	DA	–40°C to +85°C	8–Pin (2 mm x 2 mm) WDFN(TDFN) (Pb–Free)	3000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*A "microdot" placed at the end of last row of marking or just below the last row toward the center of package indicates Pb-Free.

#### PACKAGE DIMENSIONS



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

Timing-Safe is a trademark of Semiconductor Components Industries, LLC (SCILLC).

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights or the rights of others. ON Semiconductor and tesigned, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death

#### PUBLICATION ORDERING INFORMATION

#### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303–675–2175 or 800–344–3860 Toll Free USA/Canada Fax: 303–675–2176 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800–282–9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support: Deces: 424-23-200-2010

Phone: 421 33 790 2910 Japan Customer Focus Center Phone: 81–3–5817–1050 ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative